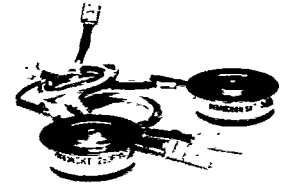


V _{DRM} V _{RRM}	t _q (T _{vj} = 125 °C)	I _{TRMS} (maximum values for continuous operation)	
		450 A	600 A
V	μs	I _{TAV} (sin. 180; T _{case} = ... °C; 50 Hz; DSC) 240 A (88 °C)	290 A (85 °C)
400	15 20	SKT 240 F 04 DS SKT 240 F 04 DT	SKT 290 F 04 DS SKT 290 F 04 DT
800	15 20	SKT 240 F 08 DS SKT 240 F 08 DT	SKT 290 F 08 DS SKT 290 F 08 DT
1000	15 20	SKT 240 F 10 DS SKT 240 F 10 DT	SKT 290 F 10 DS SKT 290 F 10 DT
1200	15 20 25	SKT 240 F 12 DS* SKT 240 F 12 DT SKT 240 F 12 DU	SKT 290 F 12 DT SKT 290 F 12 DU
1400	30	SKT 240 F 14 DV*	

Fast Thyristors with Amplifying Gate

SKT 240 F
SKT 290 F

T.25-19



Symbol	Conditions	SKT 240 F	SKT 290 F
I _{TM}	sin. 180; T _{case} = 60 °C; DSC; 50 Hz	900 A	1200 A
I _{TSM}	T _{vj} = 25 °C	4500 A	5000 A
	T _{vj} = 125 °C	4000 A	4500 A
i ² t	T _{vj} = 25 °C	101 000 A ² s	125 000 A ² s
	T _{vj} = 125 °C	80 000 A ² s	101 000 A ² s
t _{gd}	T _{vj} = 25 °C; I _G = 1 A; di _G /dt = 1 A/μs	typ. 1 μs	
t _{gr}	V _D = 0,67 · V _{DRM}	typ. 1 μs	
(di/dt) _{cr}	non-repetitive f = 50 ... 60 Hz	800 A/μs 300 A/μs	
(dv/dt) _{cr}	T _{vj} = 125 °C	500 V/μs	
I _H	T _{vj} = 25 °C; typ./max.	200 mA/400 mA	
I _L	T _{vj} = 25 °C; R _G = 33 Ω; typ./max.	1 A/2 A	
V _T	T _{vj} = 25 °C; I _T = 900 A	2,40 V	2,05 V
V _{T(TO)}	T _{vj} = 125 °C	1,45 V	1,3 V
r _T	T _{vj} = 125 °C	1 mΩ	0,75 mΩ
I _{DD} , I _{RD}	T _{vj} = 125 °C; V _{DD} = V _{DRM} ; V _{RD} = V _{RRM}	70 mA	70 mA
V _{GT}	T _{vj} = 25 °C	4 V	
I _{GT}	T _{vj} = 25 °C	250 mA	
V _{GD}	T _{vj} = 125 °C	0,25 V	
I _{GD}	T _{vj} = 125 °C	10 mA	
R _{thjc}	cont.; DSC/SSC	0,070/0,148 °C/W	
R _{thch}	DSC/SSC	0,020/0,040 °C/W	
T _{vj}		-40 ... +125 °C	
T _{stg}		-40 ... +125 °C	
F	SI units	4 ... 5 kN	
	US units	900 ... 1100 lbs.	
w		61 g	
Case	→ page B 4-21	B 8	

Features

- Capsule cases
- Hermetic ceramic to metal sealing
- Gold diffused silicon chips
- Amplifying gate

Typical Applications

- Self-commutated inverters
- DC choppers
- Motor speed control
- Inductive heating
- Uninterruptible power supplies
- Electronic welders
- General power switching applications

* Available in limited quantities

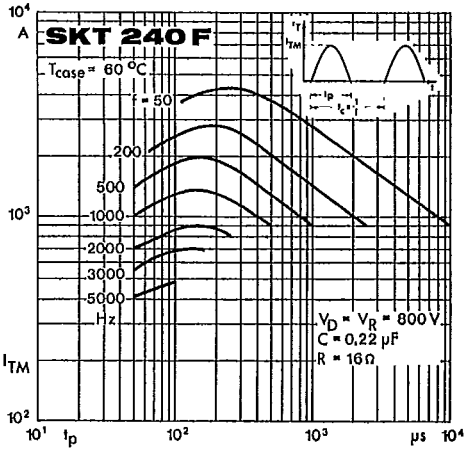


Fig. 1 a Rated peak on-state current vs. pulse duration

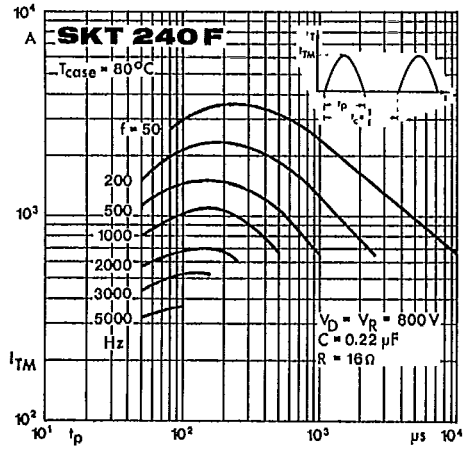


Fig. 1 b Rated peak on-state current vs. pulse duration

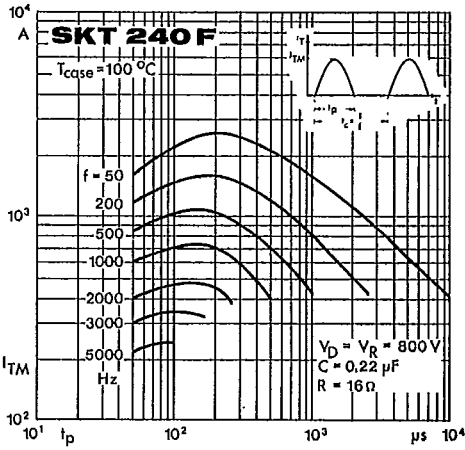


Fig. 1 c Rated peak on-state current vs. pulse duration

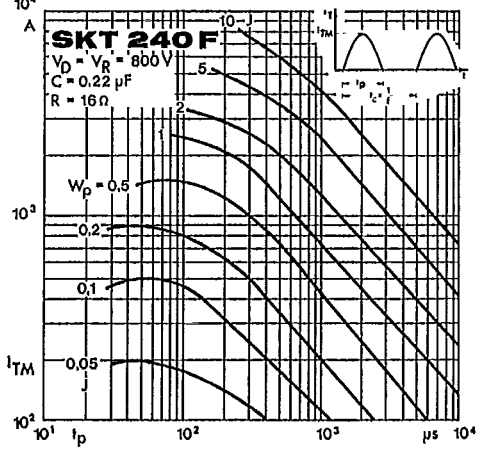


Fig. 2 Energy dissipation per pulse

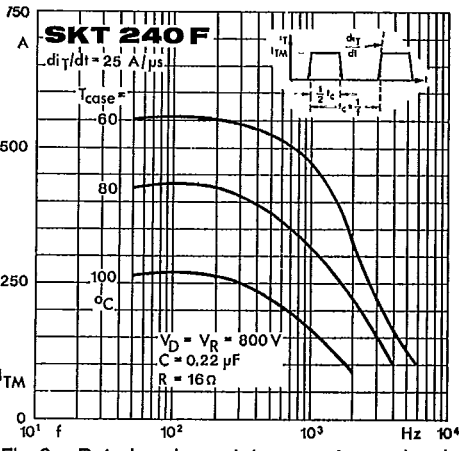


Fig. 3 a Rated peak on-state current vs. pulse duration

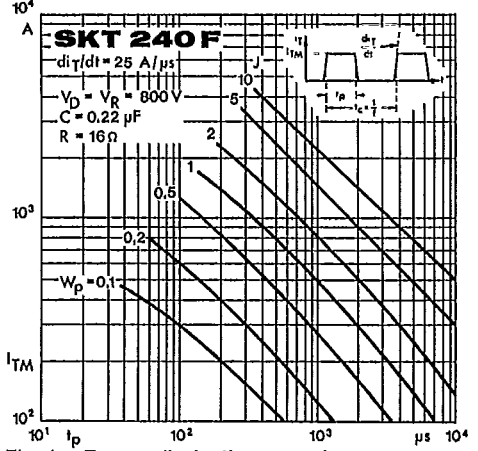


Fig. 4 a Energy dissipation per pulse

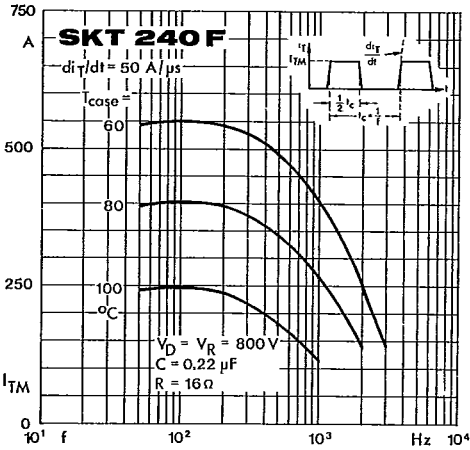


Fig. 3 b Rated peak on-state current vs. pulse duration

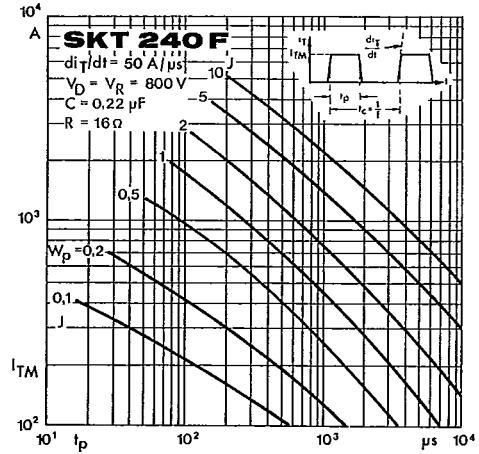


Fig. 4 b Energy dissipation per pulse

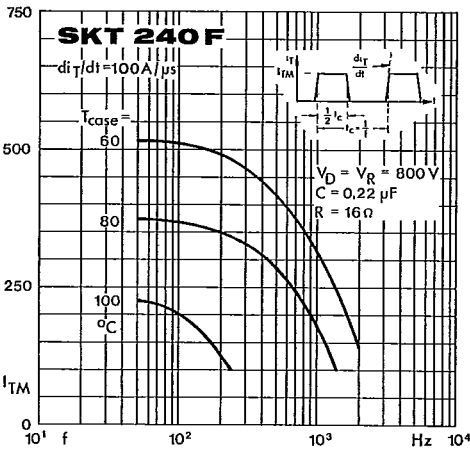


Fig. 3 c Rated peak on-state current vs. pulse duration

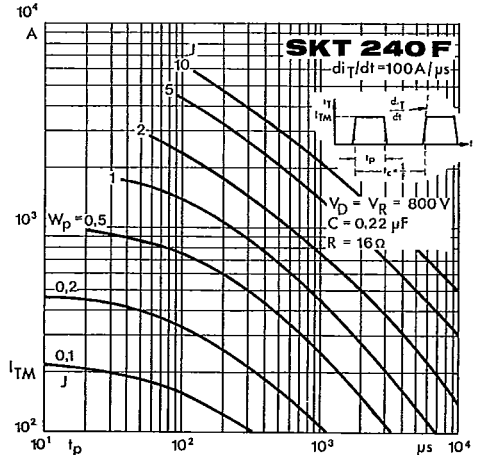


Fig. 4 c Energy dissipation per pulse

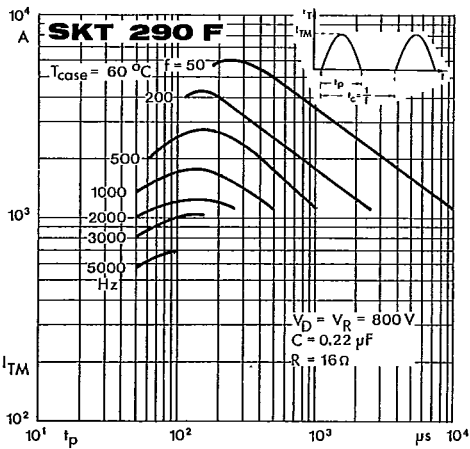


Fig. 1 a Rated peak on-state current vs. pulse duration

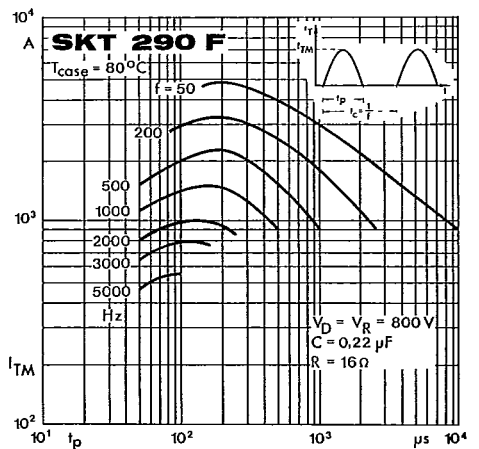


Fig. 1 b Rated peak on-state current vs. pulse duration

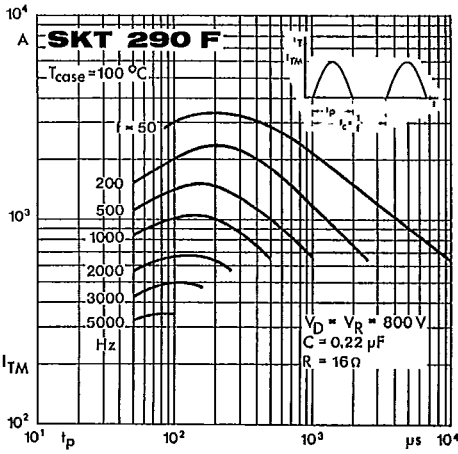


Fig. 1 c Rated peak on-state current vs. pulse duration

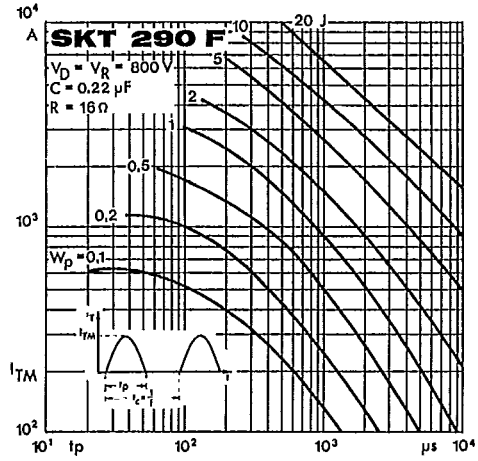


Fig. 2 Energy dissipation per pulse

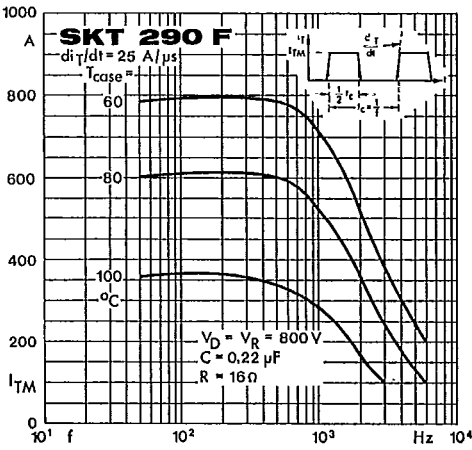


Fig. 3 a Rated peak on-state current vs. pulse duration

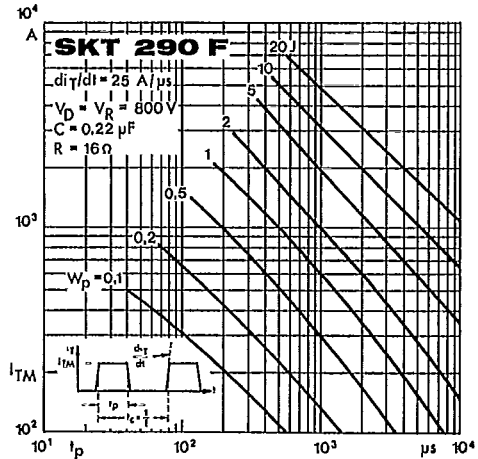


Fig. 4 a Energy dissipation per pulse

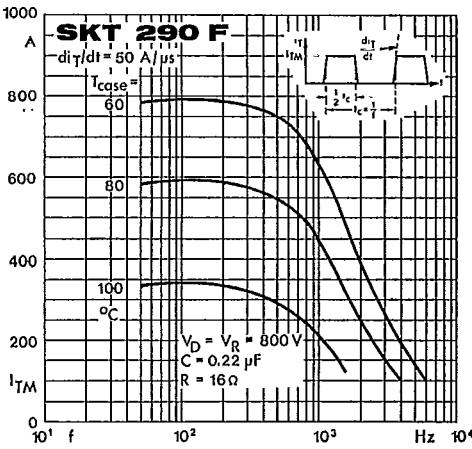


Fig. 3 b Rated peak on-state current vs. pulse duration

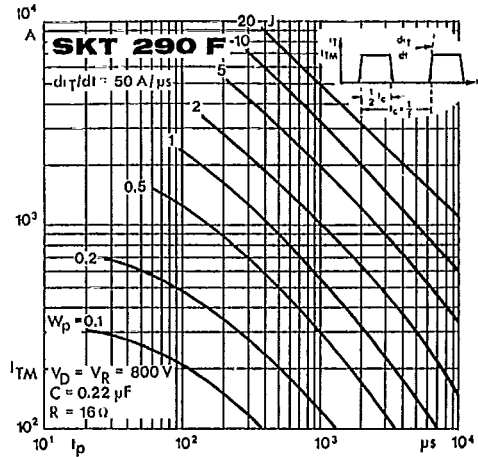


Fig. 4 b Energy dissipation per pulse

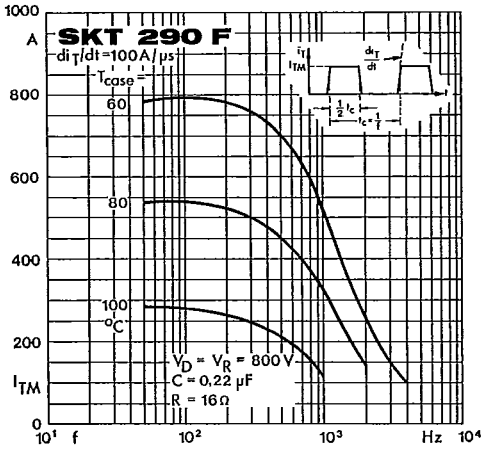


Fig. 3 c Rated peak on-state current vs. pulse duration

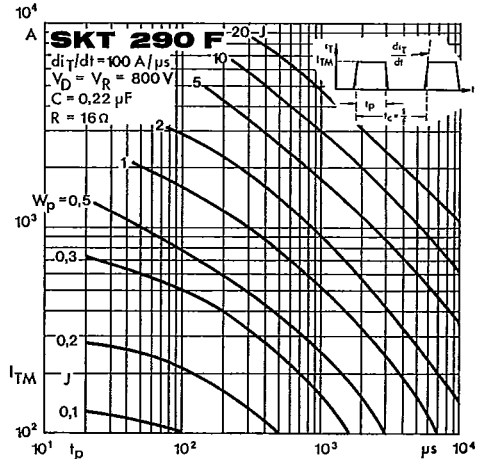


Fig. 4 c Energy dissipation per pulse

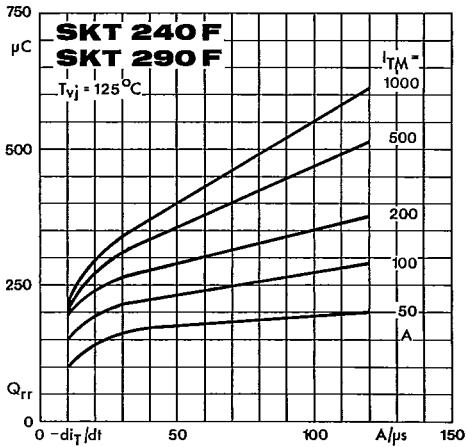


Fig. 5 Recovered charge vs. current decrease

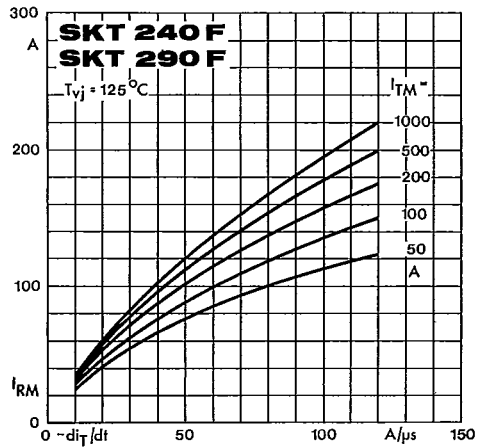


Fig. 6 Peak recovery current vs. current decrease

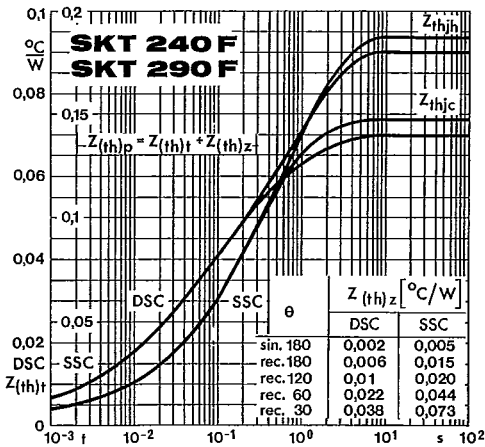


Fig. 7 Transient thermal impedance vs. time

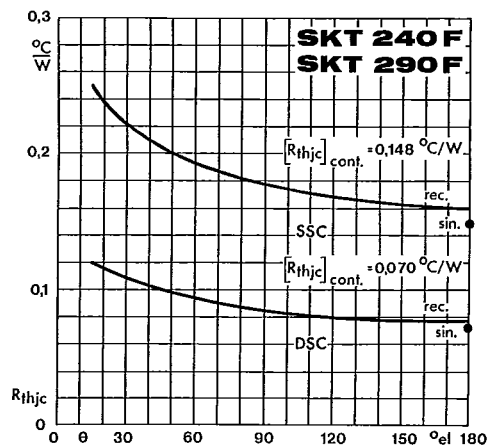


Fig. 8 Thermal resistance vs. conduction angle

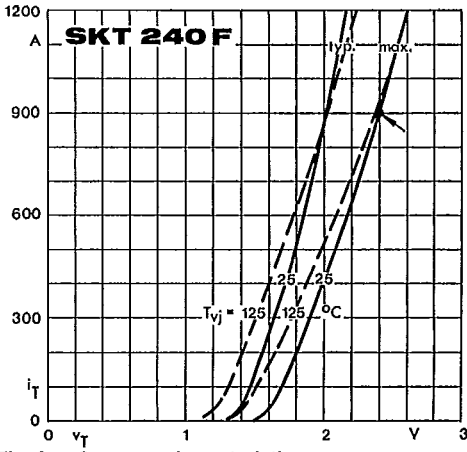


Fig. 9 a On-state characteristics

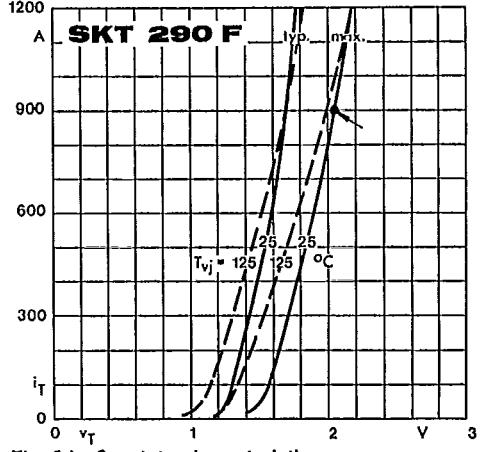


Fig. 9 b On-state characteristics

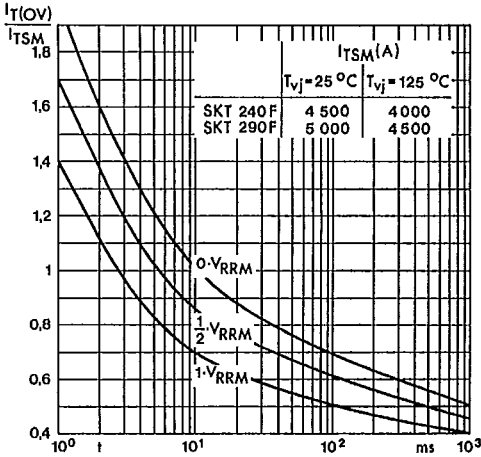


Fig. 10 Surge overload current vs. time

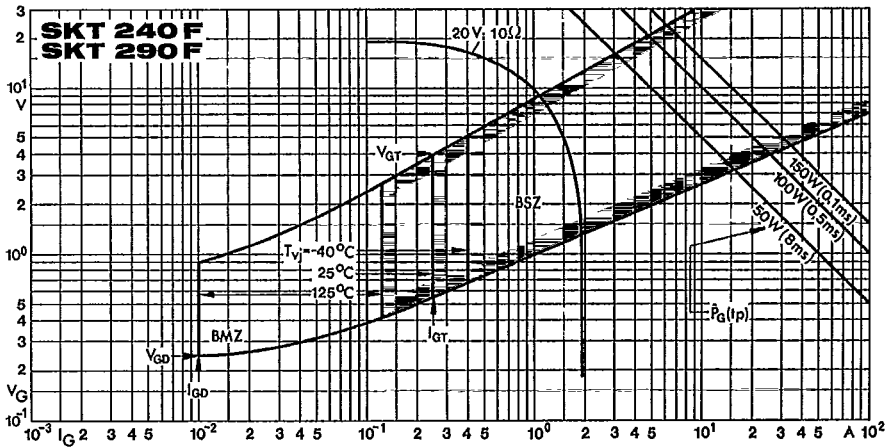


Fig. 11 Gate trigger characteristics